

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-43 (Canceled)

Claim 44 (New): A probe assembly comprising:

- a plurality of probe substrates;
- a plurality of probes disposed to correspond to a plurality of terminals of a device to be tested, subsets of said plurality of probes disposed on each of said probe substrates; and
- adjusting means for separately adjusting a planarity of each of said probe substrates to conform a planarity of contact portions of said plurality of probes to a planarity of said terminals.

Claim 45 (New): The probe assembly of claim 44, wherein said adjusting means comprises a plurality of planarity adjustment mechanisms, each configured to adjust a planarity of one of said probe substrates.

Claim 46 (New): The probe assembly of claim 45, wherein each said planarity adjustment mechanism comprises a mechanism configured to apply one of a pull or a push force to a corresponding probe substrate.

Claim 47 (New): The probe assembly of claim 45, wherein each said planarity adjustment mechanism comprises a mechanism configured to select and apply one of a pull or a push force to a corresponding probe substrate.

Claim 48 (New): The probe assembly of claim 45, wherein each said planarity adjustment mechanism comprises a plurality of mechanisms configured to apply a plurality of forces to a plurality of regions of a corresponding probe substrate.

Claim 49 (New): The probe assembly of claim 48, wherein a first of said mechanisms is configured to apply a push force to a first region of said corresponding probe substrate and a

second of said mechanisms is configured to apply selectively one of a push force or a pull force to a second region of said corresponding probe substrate.

Claim 50 (New): The probe assembly of claim 49, wherein said first region is a peripheral region of a surface of said corresponding probe substrate and said second region is a central region of said surface of said corresponding probe substrate.

Claim 51 (New): The probe assembly of claim 50 further comprising a plurality of springs, each spring configured to apply a biasing force to one of said probe substrates.

Claim 52 (New): The probe assembly of claim 51, wherein said biasing force is opposite a push force applied by one of said first mechanism or said second mechanism.

Claim 53 (New): The probe assembly of claim 44, wherein said plurality of probes are disposed to correspond to a plurality of terminals of a plurality of devices to be tested.

Claim 54 (New): The probe assembly of claim 44, wherein said device to be tested comprises a semiconductor die.

Claim 55 (New): The probe assembly of claim 54, wherein said device to be tested comprises a plurality of semiconductor dies.

Claim 56 (New): The probe assembly of claim 44 further comprising means for separately moving each of said probe substrates.

Claim 57 (New): The probe assembly of claim 44, wherein said moving comprises translating a probe substrate.

Claim 58 (New): The probe assembly of claim 57, wherein said moving comprises rotating said probe substrate.

Claim 59 (New): A probe assembly comprising:

a plurality of probe substrates;

a plurality of probes disposed to correspond to a plurality of terminals of one or more devices to be tested, subsets of said plurality of probes disposed on each of said probe substrates; and

a plurality of planarization elements, each said planarization element corresponding to one of said probe substrates and comprising a first planarizing element configured to apply one of a push or a pull force to said corresponding probe substrate.

Claim 60 (New): The probe assembly of claim 59, wherein each said planarization element further comprises a second planarizing element configured to apply a push force to said corresponding probe substrate.

Claim 61 (New): The probe assembly of claim 60, wherein:

said first planarizing element is configured to apply said one of said push or pull force to a first region of a corresponding probe substrate, and

said second planarizing element is configured to apply said push force to a second region of said corresponding probe substrate.

Claim 62 (New): The probe assembly of claim 61, wherein said first region is a central region and said second region is a peripheral region.

Claim 63 (New): The probe assembly of claim 59, wherein each said planarization element further comprises a plurality of said second planarizing elements, and wherein:

said first planarizing element is configured to apply said one of said push or pull force to a first region of a corresponding probe substrate, and

each of said second planarizing elements is configured to apply a push force to other regions of said corresponding probe substrate.

Claim 64 (New): The probe assembly of claim 63, wherein said first region is a central region and each of said other regions is a peripheral region.

Claim 65 (New): The probe assembly of claim 59 further comprising a plurality of springs, each spring configured to apply a biasing force to one of said probe substrates.

Claim 66 (New): The probe assembly of claim 65, wherein said biasing force is opposite said push force.

Claim 67 (New): The probe assembly of claim 59, wherein said device or devices to be tested comprise a semiconductor die or dies.

Claim 68 (New): The probe assembly of claim 59 further comprising a plurality of positioning elements, each said positioning element corresponding to one of said probe substrates and configured to move said corresponding probe substrate.

Claim 69 (New): The probe assembly of claim 68, wherein said moving comprises translating a probe substrate.

Claim 70 (New): The probe assembly of claim 69, wherein said moving comprises rotating said probe substrate.

Claim 71 (New): A method of planarizing a plurality of probes, wherein said probes are disposed to correspond to a plurality of terminals of one or more devices to be tested and subsets of said probes are disposed on each of a plurality of probe substrates, said method comprising:

adjusting a planarity of contact portions of said probes to correspond to a planarity of said terminals, wherein said step of adjusting comprises:

adjusting a shape of a surface of a first of said probe substrates, wherein one of said subsets of probes is attached to said surface of said first probe substrate; and

adjusting a shape of a surface of a second of said probe substrates, wherein another of said subsets of probes is attached to said surface of said second probe substrate.

Claim 72 (New): The method of claim 71, wherein said step of adjusting a shape of a surface of said first probe substrate comprises selectively applying one of a push or a pull force to a first region of said first probe substrate.

Claim 73 (New): The method of claim 71, wherein said step of adjusting a shape of a surface of said first probe substrate further comprises:

applying a pull force to a first region of said probe substrate, and

applying a push force to a second region of said probe substrate.

Claim 74 (New): The method of claim 73, wherein:

said first region corresponds to a central region of said surface of said first probe substrate,

said second region corresponds to a peripheral region of said surface of said first probe substrate.

Claim 75 (New): The method of claim 71, wherein said step of adjusting a shape of a surface of said first probe substrate further comprises applying a plurality of forces to a plurality of regions of said first probe substrate.